

RESPONSE TO RESTRICTION REQUIREMENT AND AMENDMENT
U.S. Application No: 10/026,454

REMARKS

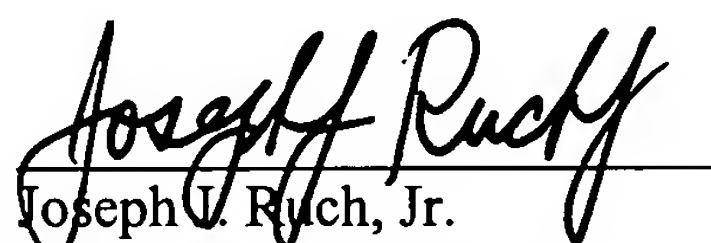
In response to the Office Action of July 24, 2002, imposing a restriction requirement between Group I (claims 5 and 6) and Group II (Claims 1-4), Applicants hereby elects Group I, claims 5 and 6. Furthermore, claims 5 and 6 have been amended to improve the form thereof, and new claims 7-12 have been added to further place the claims in desired appropriate form for examination. Thus all of the claims are now in appropriate form, and the Examiner is respectfully requested to proceed with the examination.

Early favorable action is earnestly solicited.

In the event that the Examiner believes that it may facilitate the further prosecution of this application, the Examiner is invited to contact the undersigned attorney at the local Washington, D.C. telephone number indicated below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,


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APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

5. (amended) A wiring substrate comprising: an insulating substrate having an opening; at least one electronic part disposed in the opening; and an embedding resin ~~according to claim 1~~ comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than $85 \text{ Pa} \cdot \text{s}$ in a shear rate of 8.4 s^{-1} after being allowed to stand for 24 hours at $25^{\circ}\text{C} + 1^{\circ}\text{C}$, wherein the at least one electronic part is embedded with the embedding resin.

6. (amended) A wiring substrate comprising: a core substrate; and a build-up layer provided on at least one side of the core substrate and formed by alternately laminating an insulating layer and a wiring layer, wherein at least one of the core substrate and the building-up layer has an opening penetrating therethrough, and an electronic part is disposed in the opening and embedded with an embedding resin ~~according to claim 1~~ comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than $85 \text{ Pa} \cdot \text{s}$ in a shear rate of 8.4 s^{-1} after being allowed to stand for 24 hours at $25^{\circ}\text{C} + 1^{\circ}\text{C}$.

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Claims 7, 8, 9, 10, 11 and 12 are added as new claims.

7. The embedding resin according to claim 5, wherein the acid anhydride curing agent has a viscosity at 25°C + 1°C of not higher than 170 mPa · s.

8. The embedding resin according to claim 5, which contains the filler in an amount of from 51% by weight to 74% by weight.

9. The embedding resin according to claim 5, wherein the filler contains at least one inorganic filler.

10. The embedding resin according to claim 6, wherein the acid anhydride curing agent has a viscosity at 25°C + 1°C of not higher than 170 mPa · s.

11. The embedding resin according to claim 6, which contains the filler in an amount of from 51% by weight to 74% by weight.

12. The embedding resin according to claim 6, wherein the filler contains at least one inorganic filler.